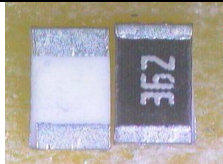


MATERIAL DECLARATION SHEET



Material Number	CR0805			
Product Line	Chip Resistors			
Compliance Date	2010/10/29			
RoHS Compliant	YES	MSL	1	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Ceramic Substrate	Ceramic	0.00381944	Aluminum oxide	1344-28-1	96%	85.56%	89.13%
				Silicon dioxide	14808-60-7	4%	3.57%	
2	Conductor Layer	Conductor glass	0.00008224	Silver	7440-22-4	96%	1.82%	1.92%
				Bismuth trioxide	1304-76-3	1%	0.025%	
				Barium oxide	1304-28-5	1%	0.025%	
				Silicon dioxide	7631-86-9	1%	0.025%	
				Boron oxide	1303-86-2	1%	0.025%	
3	Resistive Element	Resistor glass	0.00004328	Ruthenium dioxide	12036-10-1	25%	0.25%	1.01%
				Silver	7440-22-4	40%	0.40%	
				Palladium	7440-05-3	15%	0.15%	
				Lead oxide glass	1317-36-8	20%	0.20%	
4	Over Coating	Epoxy	0.0000665	Epoxy	29690-82-2	100%	1.55%	1.55%
5	Marking	Epoxy	0.00000361	Epoxy	25068-38-6	100%	0.08%	0.08%
6	End Terminal	Nickel Chromium	0.00000337	Nickel	7440-02-0	80%	0.06%	0.08%
				Chromium III	7440-47-3	20%	0.02%	
7	Ni Plating	Nickel	0.00014111	Nickel	7440-02-0	100%	3.29%	3.29%
8	Sn Plating	Matte Tin	0.00012589	Tin	7440-31-5	100%	2.94%	2.94%
			Total weight	0.00428544				

MATERIAL DECLARATION



This Document was updated on: 10.29.2010

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.
2. RoHS exemption – 5 – lead in glass of... electronic components...